

Features

- Advanced Trench Process Technology
- High Density Cell Design for Ultra Low On-Resistance
- Reliable and Rugged
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 1.79°C/W Junction to Case (Note 2)

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V_{DS}	-100	V	
Gate-Source Voltage	V_{GS}	±20	V	
Continuous Drain Current	I_D	$T_C=25^\circ C$	-20	A
		$T_C=100^\circ C$	-12	A
Pulsed Drain Current	I_{DM}	-72	A	
Single Pulsed Avalanche Energy (Note 3)	E_{AS}	225	mJ	
Total Power Dissipation	P_D	70	W	

Note:

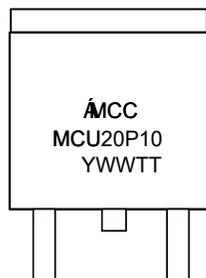
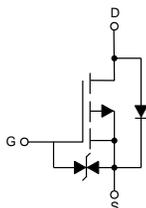
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. copper, in a still air environment with $T_A=25^\circ C$.

2. Surface Mounted on FR4 Board, $t \leq 10$ sec.

3. $L=0.5mH$, $V_{DD}=-50V$, $V_G=-10V$, $R_G=25\Omega$, Starting $T_J=25^\circ C$.

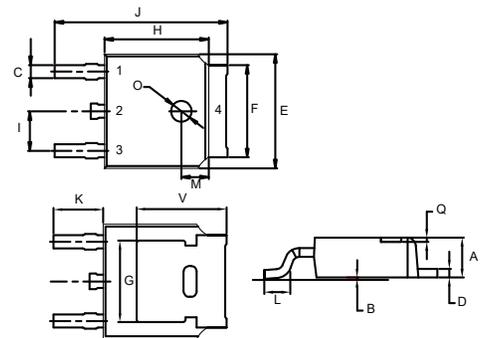
Ordering Information



YWWTT: 5 codes in total
Y is the year
WW is the cycle
TT is the line type

P-CHANNEL MOSFET

DPAK(TO-252)



- 1. Gate
- 2,4. Drain
- 3. Source

DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.087	0.094	2.20	2.40	
B	0.000	0.005	0.00	0.13	
C	0.026	0.034	0.66	0.86	
D	0.018	0.023	0.46	0.58	
E	0.256	0.264	6.50	6.70	
F	0.201	0.215	5.10	5.46	
G	0.190		4.83		TYP.
H	0.236	0.244	6.00	6.20	
I	0.086	0.094	2.18	2.39	
J	0.386	0.409	9.80	10.40	
K	0.114		2.90		TYP.
L	0.055	0.067	1.40	1.70	
M	0.063		1.60		TYP.
O	0.043	0.051	1.10	1.30	
Q	0.000	0.012	0.00	0.30	
V	0.211		5.35		TYP.

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-100			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 20	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-100V, V_{GS}=0V$			-1	μA
Gate-Threshold Voltage ^(Note 4)	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.9	-3	V
Drain-Source On-Resistance ^(Note 4)	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-16A$	85	100	116	m Ω
Forward Transconductance ^(Note 4)	g_{FS}	$V_{DS}=-50V, I_D=-10A$	5			S
Dynamic Characteristics^(Note 5)						
Input Capacitance	C_{iss}	$V_{DS}=-25V, V_{GS}=0V, f=1MHz$		2100		pF
Output Capacitance	C_{oss}			590		
Reverse Transfer Capacitance	C_{rss}			140		
Total Gate Charge	Q_g	$V_{DS}=-80V, V_{GS}=-10V, I_D=-16A$		61		nC
Gate-Source Charge	Q_{gs}			14		
Gate-Drain Charge	Q_{gd}			29		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=-50V, I_D=-16A$ $V_{GS}=-10V, R_{GEN}=9.1\Omega$		16		ns
Turn-On Rise Time	t_r			73		
Turn-Off Delay Time	$t_{d(off)}$			34		
Turn-Off Fall Time	t_f			57		
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C=25^\circ C$			-18	A
Body Diode Voltage	V_{SD}	$I_S=-10A, V_{GS}=0V$			-1.2	V
Reverse Recovery Time	t_{rr}	$I_F=-16A, di/dt=100A/\mu s$		88.3		ns
Reverse Recovery Charge	Q_{rr}				65.9	
Forward Turn-on Time	t_{on}	Intrinsic Turn-On Time is Negligible(Turn-On is Dominated by L_S+L_D)				

Note 4. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

5. Guaranteed by Design, Not Subject to Production Testing.

Curve Characteristics

Fig. 1 - Typical Output Characteristics

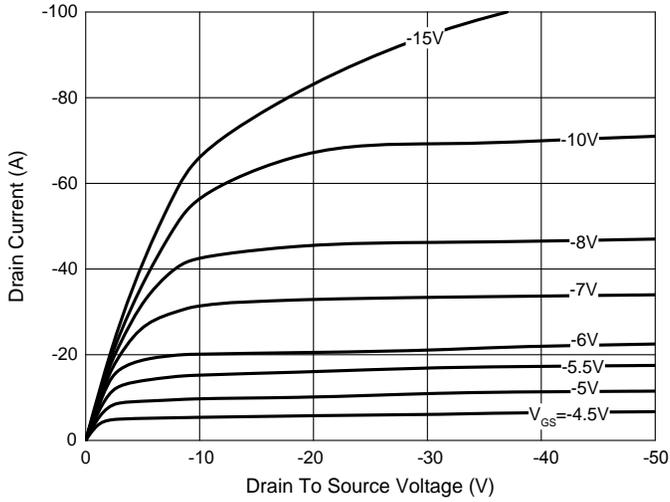


Fig. 2 - $R_{DS(ON)}$ —Temperature

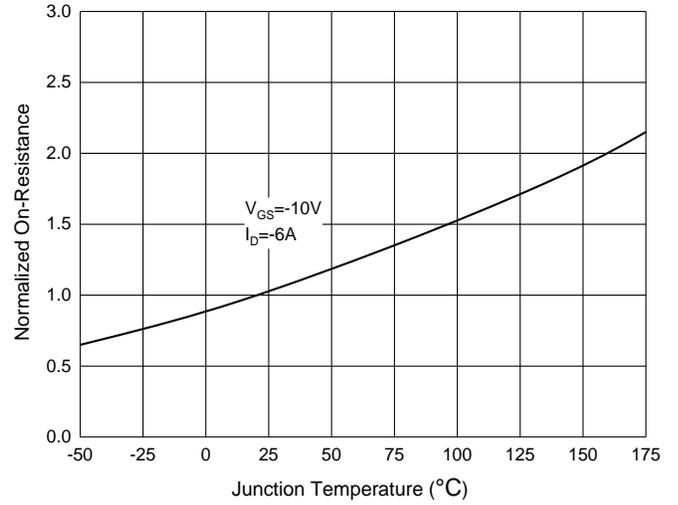


Fig. 3 - $R_{DS(ON)}$ — I_D

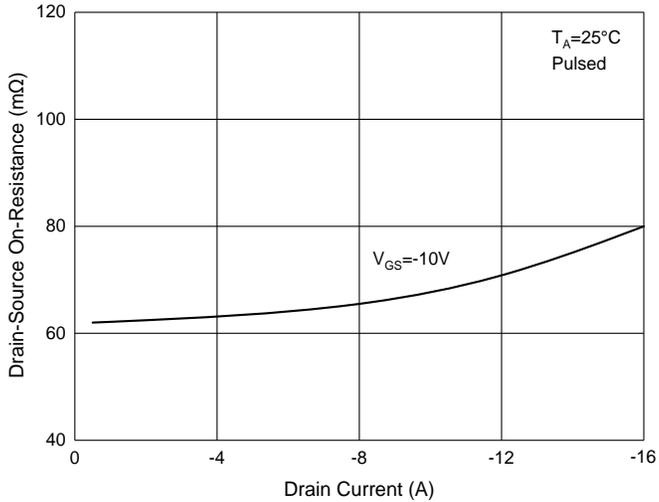


Fig. 4 - Total Gate Charge Characteristics

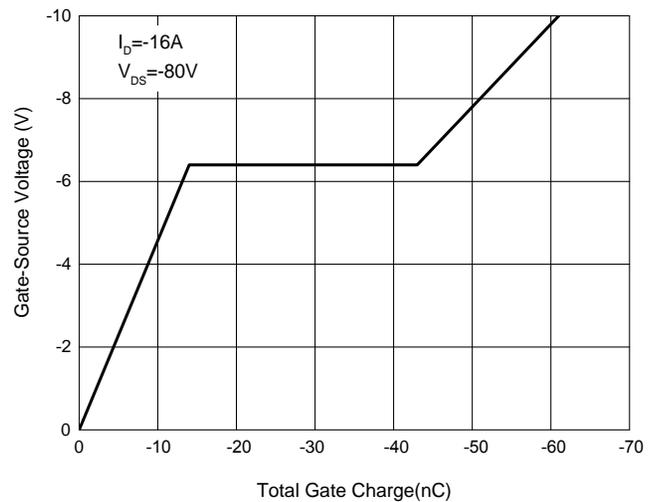
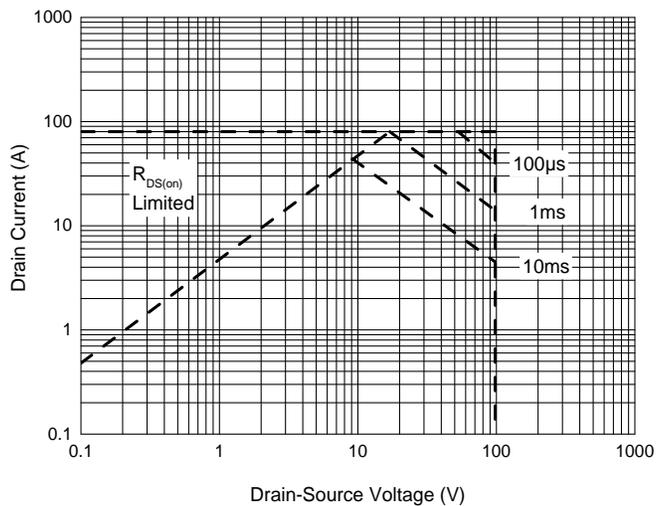


Fig. 5 - Safe Operation Area



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 2.5Kpcs/Reel

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